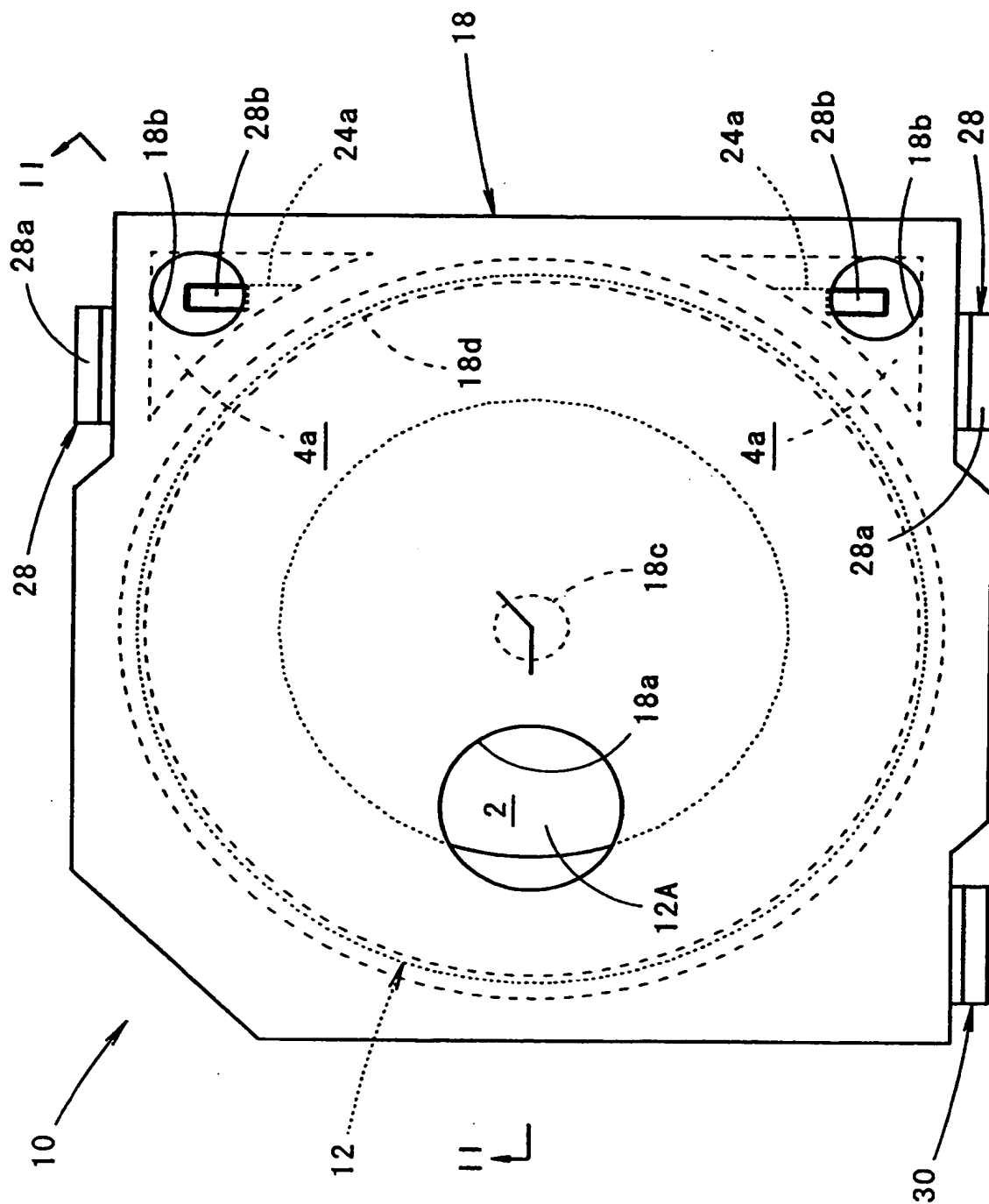


FIG. 1



This cross-sectional diagram illustrates a multi-layered electronic assembly. The assembly is housed within a rectangular frame, likely a printed circuit board (PCB), which is shown in cross-section with diagonal hatching. The assembly consists of several stacked layers and components:

- Top Layer (26a):** The uppermost layer, which appears to be a conductive or insulating substrate.
- Second Layer (26b):** A layer directly beneath the top layer, containing various components.
- Third Layer (26c):** A layer below the second, featuring a central rectangular opening (12) and a smaller opening (14) on the right side.
- Fourth Layer (26d):** A layer below the third, containing a central rectangular opening (12) and a smaller opening (14) on the right side.
- Bottom Layer (26e):** The lowest layer, which is a conductive or insulating substrate.
- Central Opening (12):** A large rectangular opening in the center of the assembly, through which a component (2) is visible.
- Right Side Opening (14):** A smaller rectangular opening on the right side of the assembly, through which a component (4) is visible.
- Wiring and Connections:** Various wires and connections are shown, including a wire (18a) entering from the top left, a wire (18b) entering from the top right, and a wire (18c) entering from the bottom right. A wire (18d) is also shown connecting to the central opening (12).
- Labels and Dimensions:** The diagram includes numerous labels for components and dimensions: 2, 4, 6, 10, 12, 14, 16, 18a, 18b, 18c, 18d, 22A, 22B, 24a, 24b, 26a, 26b, 26c, 26d, 26e, 28b, 4a, 4b, and 18. Some labels are underlined (e.g., 2, 4, 6, 12, 14, 18a, 18b, 18c, 18d, 22A, 22B, 24a, 24b, 26a, 26b, 26c, 26d, 26e).

FIG. 3

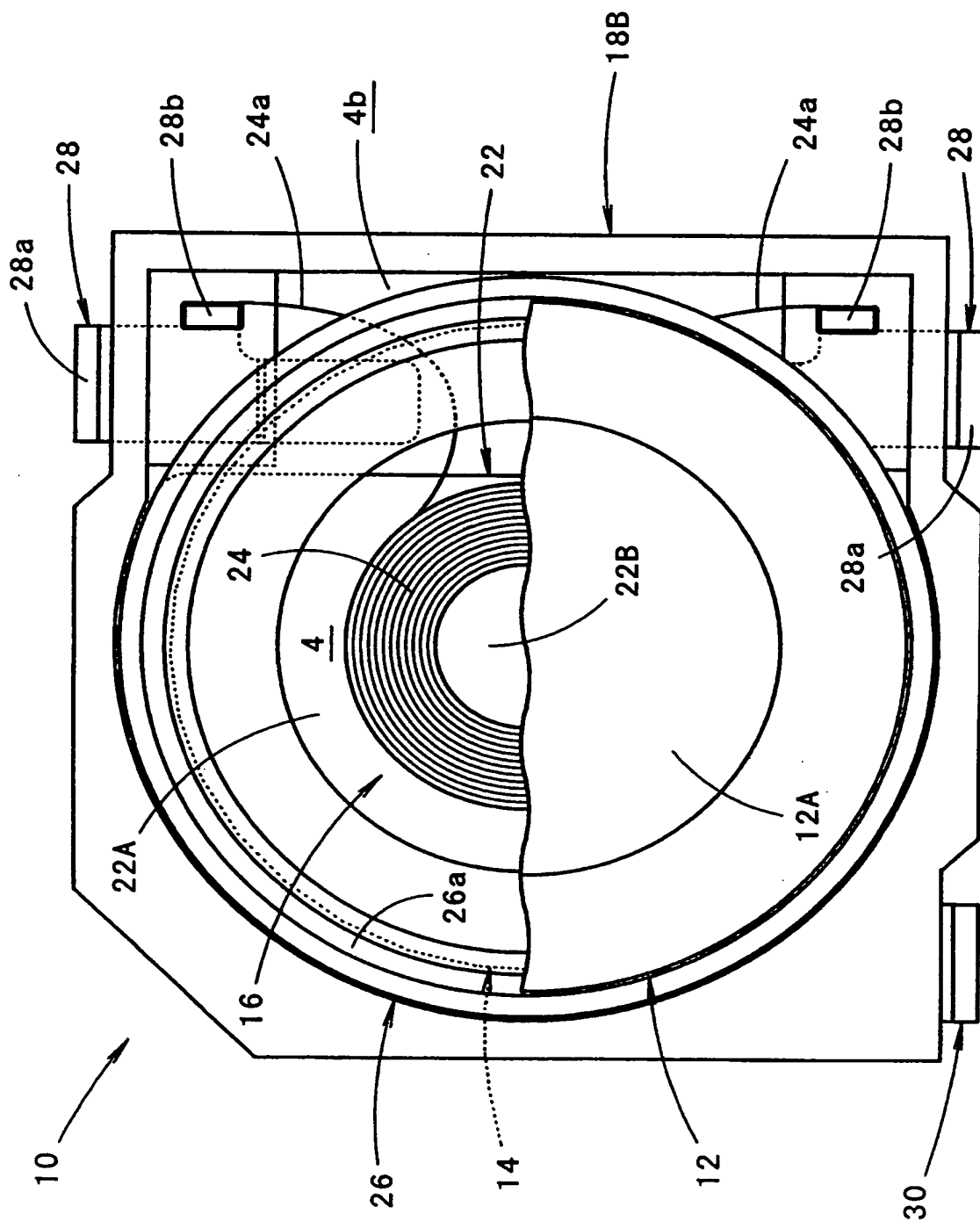
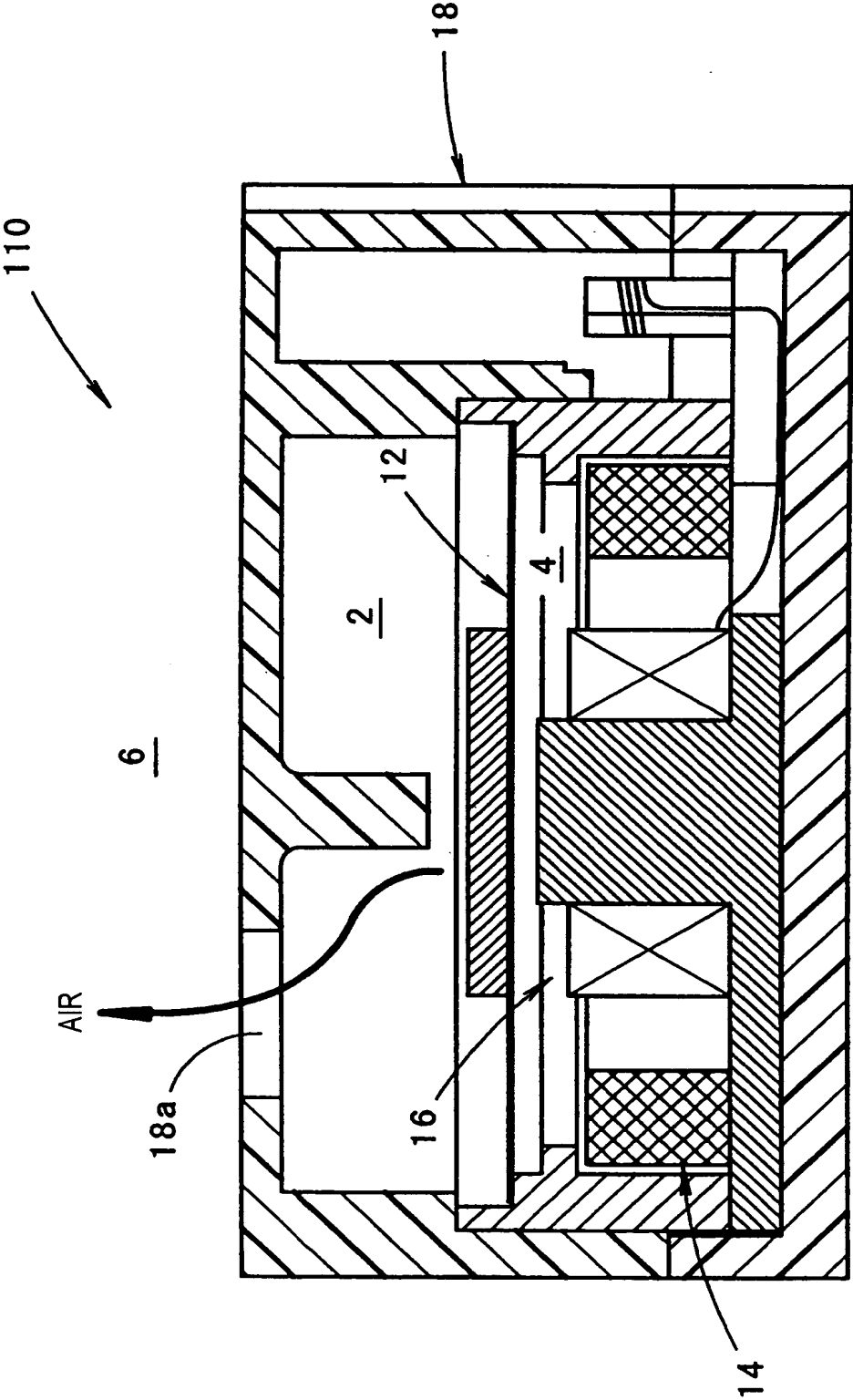


FIG. 4



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FIG. 5

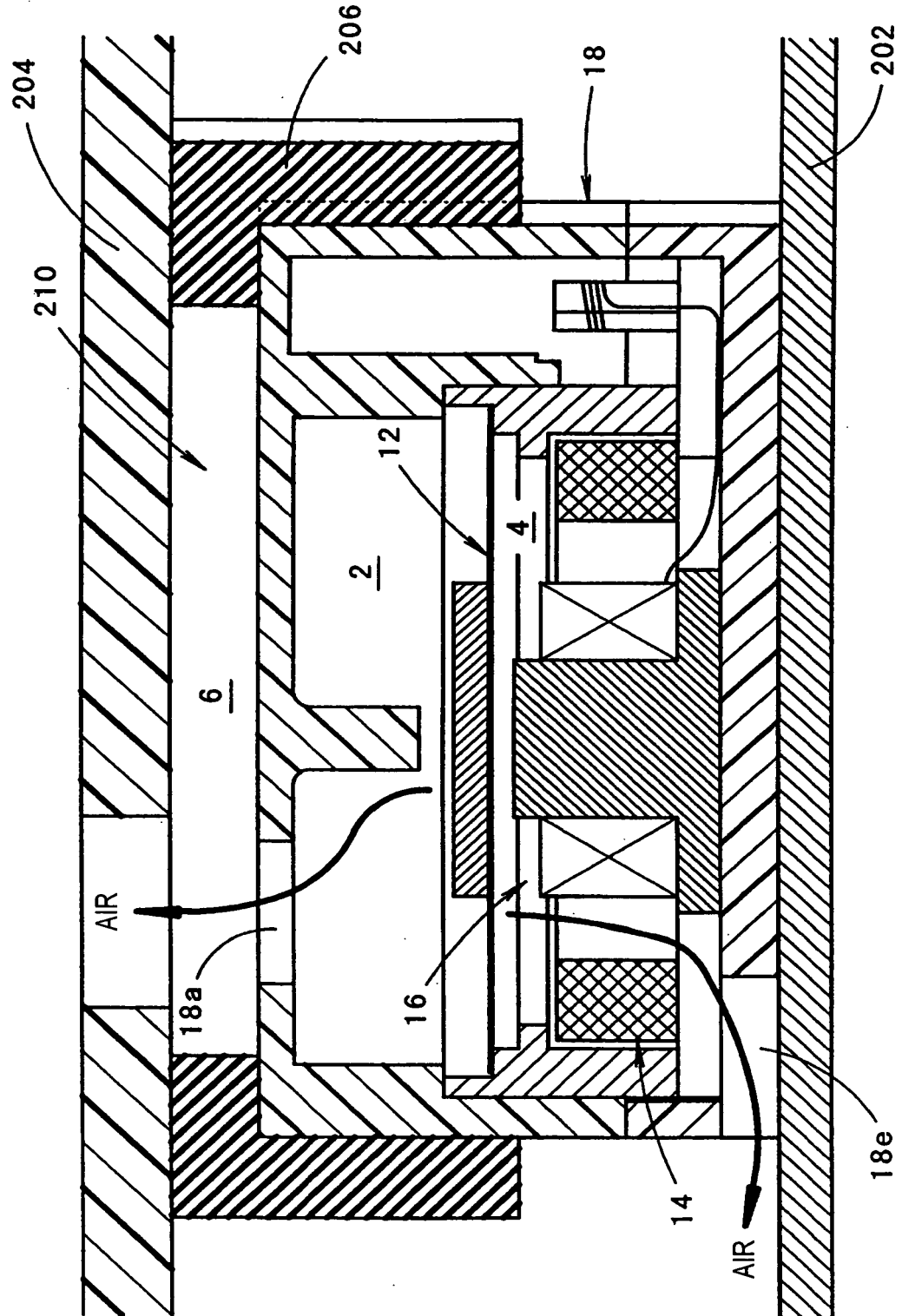


FIG. 6

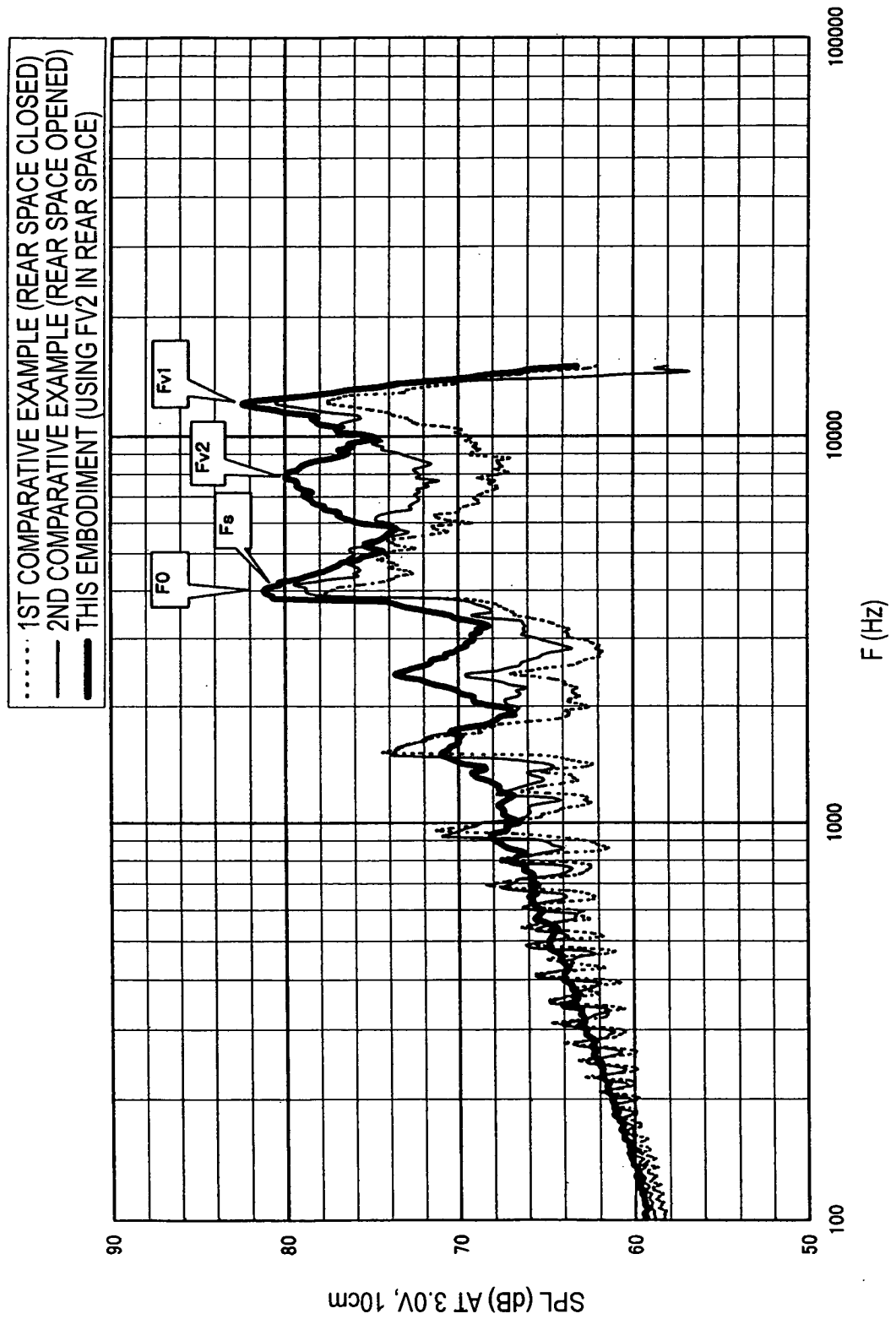


FIG. 7

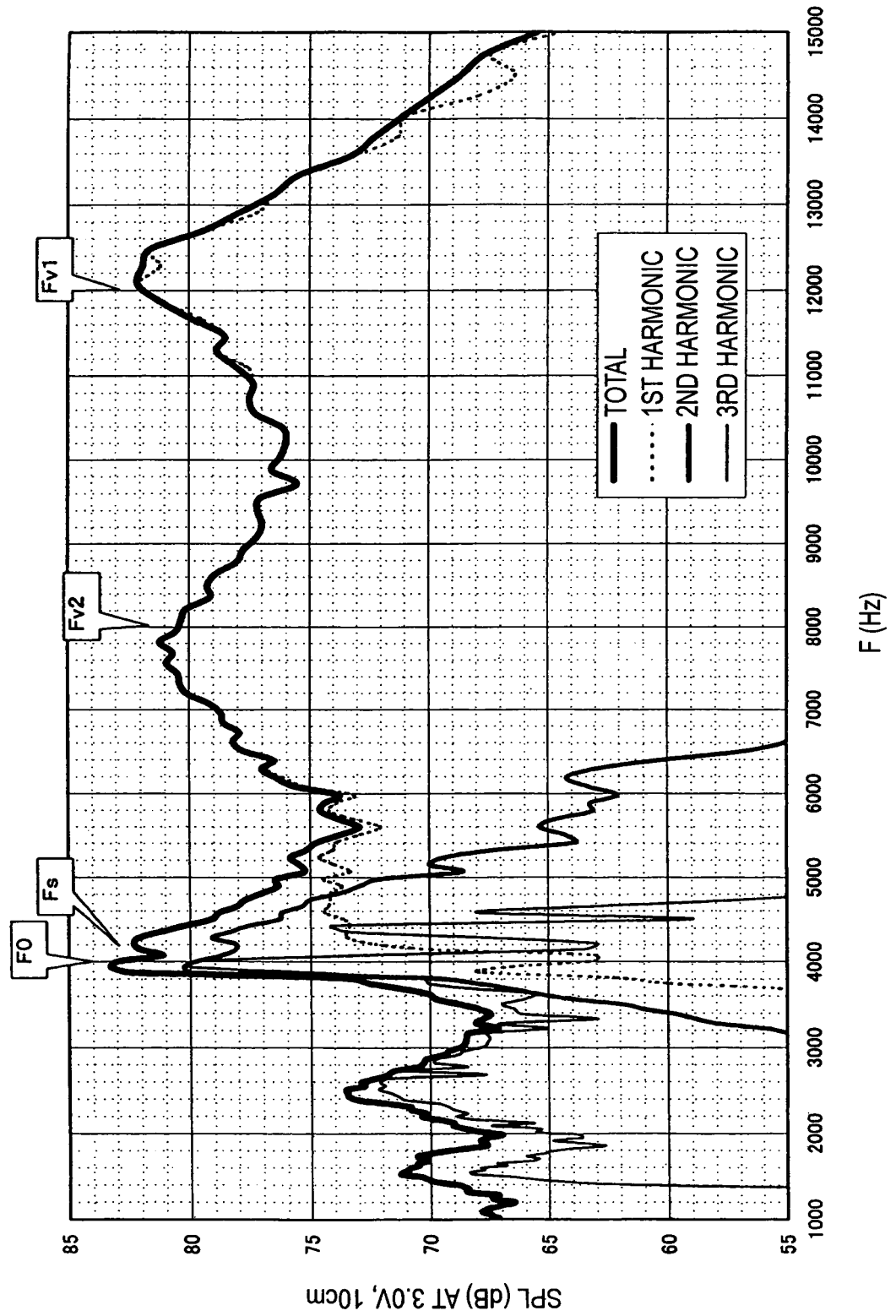


FIG. 8

